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LCD TV SERVICE MANUAL

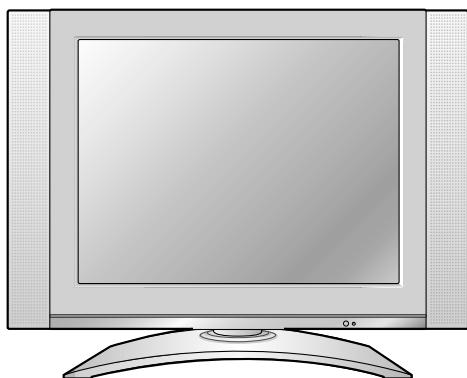
CHASSIS : ML-041B

MODEL : RZ-20LA66(RZ-20LA66 Rev A)

***() ID LABEL Model No.**

CAUTION

BEFORE SERVICING THE CHASSIS,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



***Same looking with new chassis**

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SAFETY PRECAUTIONS

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by Δ in the Schematic Diagram and Replacement Parts List.

It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards.

Do not modify the original design without permission of manufacturer.

General Guidance

An **isolation Transformer** should always be used during the servicing of a receiver whose chassis is not isolated from the AC power line. Use a transformer of adequate power rating as this protects the technician from accidents resulting in personal injury from electrical shocks.

It will also protect the receiver and its components from being damaged by accidental shorts of the circuitry that may be inadvertently introduced during the service operation.

If any fuse (or Fusible Resistor) in this TV receiver is blown, replace it with the specified.

When replacing a high wattage resistor (Oxide Metal Film Resistor, over 1W), keep the resistor 10mm away from PCB.

Keep wires away from high voltage or high temperature parts.

X-RAY Radiation

Warning:

The source of X-RAY RADIATION in this TV receiver is the High Voltage Section and the LCD PANEL.

For continued X-RAY RADIATION protection, the replacement panel must be the same type panel as specified in the Replacement Parts List.

To determine the presence of high voltage, use an accurate high impedance HV meter.

Adjust brightness, color, contrast controls to minimum.

Measure the high voltage.

The meter reading should indicate

$23.5 \pm 1.5\text{KV}$: 14-19 inch, $26 \pm 1.5\text{KV}$: 19-21 inch,

$29.0 \pm 1.5\text{KV}$: 25-29 inch, $30.0 \pm 1.5\text{KV}$: 32 inch

If the meter indication is out of tolerance, immediate service and correction is required to prevent the possibility of premature component failure.

Before returning the receiver to the customer,

always perform an **AC leakage current check** on the exposed metallic parts of the cabinet, such as antennas, terminals, etc., to be sure the set is safe to operate without damage of electrical shock.

Leakage Current Cold Check(Antenna Cold Check)

With the instrument AC plug removed from AC source, connect an electrical jumper across the two AC plug prongs. Place the AC switch in the on position, connect one lead of ohm-meter to the AC plug prongs tied together and touch other ohm-meter lead in turn to each exposed metallic parts such as antenna terminals, phone jacks, etc.

If the exposed metallic part has a return path to the chassis, the measured resistance should be between $1\text{M}\Omega$ and $5.2\text{M}\Omega$.

When the exposed metal has no return path to the chassis the reading must be infinite.

An other abnormality exists that must be corrected before the receiver is returned to the customer.

Leakage Current Hot Check (See below Figure)

Plug the AC cord directly into the AC outlet.

Do not use a line Isolation Transformer during this check.

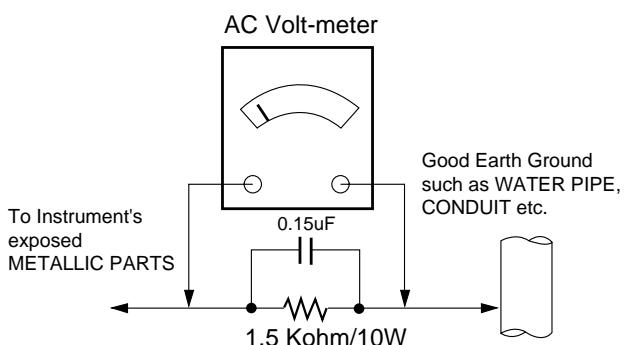
Connect 1.5K/10watt resistor in parallel with a $0.15\mu\text{F}$ capacitor between a known good earth ground (Water Pipe, Conduit, etc.) and the exposed metallic parts.

Measure the AC voltage across the resistor using AC voltmeter with 1000 ohms/volt or more sensitivity.

Reverse plug the AC cord into the AC outlet and repeat AC voltage measurements for each exposed metallic part. Any voltage measured must not exceed 0.75 volt RMS which corresponds to 0.5mA.

In case any measurement is out of the limits specified, there is possibility of shock hazard and the set must be checked and repaired before it is returned to the customer.

Leakage Current Hot Check circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before:
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.
- CAUTION:** A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.
2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe.
Do not test high voltage by "drawing an arc".
3. Do not spray chemicals on or near this receiver or any of its assemblies.
4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)
CAUTION: This is a flammable mixture.
Unless specified otherwise in this service manual, lubrication of contacts is not required.
5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.
6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.
7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.
Always remove the test receiver ground lead last.
8. *Use with this receiver only the test fixtures specified in this service manual.*

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called

Electrostatically Sensitive (ES) Devices. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the

unit under test.

2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
 3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
 4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
 5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
 6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
 7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.
- CAUTION:** Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.
8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500° F to 600° F.
2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.
3. Keep the soldering iron tip clean and well tinned.
4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle.
Do not use freon-propelled spray-on cleaners.
5. Use the following unsoldering technique
 - a. Allow the soldering iron tip to reach normal temperature. (500° F to 600° F)
 - b. Heat the component lead until the solder melts.
 - c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.
CAUTION: Work quickly to avoid overheating the circuitboard printed foil.
6. Use the following soldering technique.
 - a. Allow the soldering iron tip to reach a normal temperature (500° F to 600° F)
 - b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.
 - c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.
- CAUTION:** Work quickly to avoid overheating the circuit board printed foil.
- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush.
(It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife. Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.
Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

1. Application range

This specification is applied to ML-041B chassis.

2. Requirement for Test

Testing for standard of each part must be followed in below condition.

- (1) Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$
- (2) Humidity: $65\% \pm 10\%$
- (3) Power: Standard input voltage (AC 100-240V, 50/60Hz)
- (4) Measurement must be performed after heat-run more than 30min.
- (5) Adjusting standard for this chassis is followed a special standard.

3. General Specification

No.	Item	Specification	Remark
1	Maker	LPL	LPL
	Type	TFT Color LCD Module	
	ActiveDisplay Area	20.1 inches(380.16mm) diagonal(Aspect 4:3)	
	Pixel Pitch [mm]	0.6375mm(H)x0.6375mm(V)xRGB	
	Electrical Interface	LVDS	
	Color Depth	8BIT, 16,777,216 colors	
	Size [mm]	450(H)x 348.7(V)x20(D)	
	Surface Treatment	Glare, Hard Coating(3H)	
	Operating Mode	Normally Black	
	Back light Unit	6 CCFL(6 lamps)	
	R/T Typ.	16ms(R.T.:7/10ms + F.T.:18/20ms)	
2	Maker	AUO	AUO
	Type	TFT Color LCD Module	
	ActiveDisplay Area	20.1 inches(510.00mm) diagonal	
	Pixel Pitch [mm]	0.6376mm(H)x0.6375mm(V)xRGB	
	Electrical Interface	TTL	
	Color Depth	8-BIT 16,777.216 Colors	
	Size [mm]	434(H)x331.6(V)x29.6(D)	
	Surface Treatment	Hard Coating, AR, Glare (3H)	
	Operating Mode	Normally Black	
	Back light Unit	6 CCFL(6 lamps)	
	R/T Typ.	16ms	
3	Maker	CMO	CMO
	Type	TFT Color LCD Module	
	ActiveDisplay Area	20.1 inches(510.00mm) diagonal	
	Pixel Pitch [mm]	0.6375mm(H)x0.6375mm(V)xRGB	
	Electrical Interface	TTL	
	Color Depth	8-BIT 16,777.216 Colors	
	Size [mm]	448(H)x339.6(V)x25(D)	
	Surface Treatment	Anti Glare, Hard Coating(3H)	
	Operating Mode	Normally Black	
	Back light Unit	6 CCFL(6 lamps)	
	R/T Typ.	16ms(R.T.:5/7ms + F.T.:11/14ms)	

4. Feature and Function

No.	Item	Specification	Remark
1	Teletext	TOP, FLOF	Top(option)
2	REMOCON	NEC Code	PAL/ NTSC
3	CVBS VIDEO Input	1	Rear
4	S-VIDEO Input	1	Rear
5	Component input	1	Rear (option, NT)
6	PERI TV Connector	Full SCART : 1	Rear (option,EU)
7	H/p input	1	Rear
8	RS-232	NO	
9	Discrete IR	NO	
10	2 Carrier Stereo	BG, DK	
11	NICAM Stereo	BG, I, LL'	
12	2 Carrier Dual	BG, DK	
13	NICAM Dual	BG, I, LL'	
14	DW(Double Window) Mode	X	
15	MW(Multi Window) Mode	X	
16	Film Mode	O	
17	Noise Reduction	X	
18	Progressive Scan	O	
19	Motion Detection	X	
20	SRS WOW	X	
21	wivel Speaker	X	
22	Ez-pip	X	
23	ARC	O	
24	DRP	O	
25	DCDI	X	
26	HDCP	X	

5.Optical Character

No.	Item	Specification				Remark
			LPL	CMO	CMO	
1	Viewing Angle <CR ≥10>	R/L, U/D	85/85 85/85	80/80 75/65	85/85 90/90	
2	Luminance	Luminance(cd/ m ²)	400	450	450	Typical
		Variation	1.3	1.3	1.3	MAX/MIN
3	Contrast Ratio		400	500	600	ALL white/All black
4	CIE Color Coordinates	WHITE W _X W _Y	Typ. 0.289 0.335	0.285 0.293	0.31 0.33	
		RED W _r Y _r	Typ. 0.692 0.335	0.692 0.332	0.64 0.34	
		Green X _g Y _g	Typ. 0.289 0.583	0.276 0.601	0.29 0.61	
		Blue X _b Y _b	Typ. 0.143 0.909	0.142 0.075	0.14 0.07	

6.Engineering Specification

No.	Item	Specification			Remark
1	Power Supply	H/V Sync	Video	Power Consumption	LED Color
	Normal	On/On	Active	≤ 65W	GREEN
	Stand By	Off/On		≤ 1W	
	Suspend Mode	On/Off	Off	≤ 1W	LED
	DPM Off Mode	Off/Off		≤ 1W	
	Cut-off Switch off	-	-	0W	OFF
				PBP SWAP ► ON/OFF	
	ITEM	Spectification			Remark
2	D-SUB Pin Configuraion	1: RED 3: Blue: 5: S.T(GND) 7: Green GND 9: N.C 11: ID0(GND) 13: H-Sync 15: SCL	2: Green 4: ID2(GND) 6: RED GND 8: Blue GND 10: D-GND 12: SDA 14: V-Sync Shell: GND		10: Digital GND
3	Control Function	1) Contrast/Brightness 2) H-Position/V-Position 3) Tracking : Clock/ Phase 4) Auto Configure RESET			
4	Comoponent Jack	1: Y 3: Pb 5: Pr			Middle east/ NTSC Area
5	D4 Jack (525i, 525p, 750p, 1125i)	1: Y GND 2: Pb 5: Pr 7: LINE1 Ready 9: Line2 11: Line3 13: Line3 ready	2: Y GND 4: Pb GND 6: Pr GND 8: LINE1 10: Line2 Ready 12: SWITCH GND 14: SWITCH		JAPAN Only

6-2.Power

NO	Item	Min	Typ	Max	Unit	Remark
1	AC Power Shut Down Voltage	90		264	V	
2	DC Voltage, Inverter	22.8	24	25.2	V	
3	DC Voltage, LCD Panel	11.4	12	12.6	V	
4	DC Voltage, Audio	14.0	15	16.0	V	
5	DC Voltage, Tuner(5)	4.5	5	5.5	V	
	DC Voltage, Tuner(9)	8.5	9	9.5	V	Japan only
6	DC Voltage, Tuning(31)	31	33	35	V	
7	DC Voltage, VCTi(5)	4.5	5	5.5	V	
	DC Voltage, VCTi(8)	7.5	8	8.5	V	
8	DC Voltage, VCTi(3.3)	3.1	3.3	3.5	V	
	DC Voltage, VCTi(1.8)	1.6	1.8	2.0	V	
9	DC Voltage, GM2221 (3.3)	3.1	3.3	3.5	V	
	DC Voltage, GM2221 (1.8)	1.6	1.8	2.0	V	
10	DC Voltage, Digital (3.3)	2.8	3.3	3.8	V	
11	DC Voltage, Digital (5)	4.5	5	5.5	V	

6-3. External Interface

NO	Item	Min	Typ	Max	Unit	Remark
1.	Video Input Level	0.85	1	1.15	Vpp	EN-50049
2.	Audio Input Level	0.4	0.5	0.6	V	NTSC:0.4Vrms(Typ)
3.	Audio Input Frequency Response	0.1		7	KHz	
4.	Audio Input S/N	40			DB	
5.	Audio Input Distortion			2	%	
6.	Audio Input Dynamic Range	2			V	
7.	Video Output Level	0.85	1	1.15	Vpp	
8.	Video Output Frequency Response	3.8			MHz	
9.	Video Output S/N	40			DB	
10.	Audio Output Level	0.4	0.5	0.6	V	
11.	Audio Output Frequency Response	0.1		7	KHz	
12.	Audio Output S/N	40			DB	
13.	Audio Output Distortion			2	%	
14.	Video Input Level, R/G/B	0.6	0.7	0.8	Vpp	75 ohm
15.	Video Input Level, Component(Y, PB, PR)	0.6	0.7	0.8	Vpp	75 ohm
16.	RGB Input Resolution, Vertical		768		Pixel	Only 20"
17.	RGB Input Resolution, Horizontal		1280		Pixel	640 Pixel 480
18.	RGB Input Horizontal Frequency				KHz	See table 5-5
19.	RGB Input Frame Rate				Hz	See table 5-5

6-4. The Others

NO	Item	Min	Typ	Max	Unit	Remark
1	Search Sensitivity			-85	dBm	
2	Soft Ware Functionality Test					
3	REMOCON Working Sensitivity, Straight	0.1		10	m	
4	REMOCON Working Sensitivity, T/B/L/R	0.1		9	m	30 degree
5	Closed Caption Sensitivity			-70	dBm	NTSC ONLY
6	Teletext Sensitivity			-70	dBm	

ADJUSTMENT INSTRUCTION

1. Application Object

This instruction is for the application to the LCD TV.

2. Adjustment

2.1 Adjustment overview

The unit is set to automatically adjust using the factory automation equipment. However when errors occur, it should be adjusted manually.

2.2 Auto Gain/Offset adjustment

2.2.1 RF Mode adjustment

2.2.1.1 Adjustment preparation

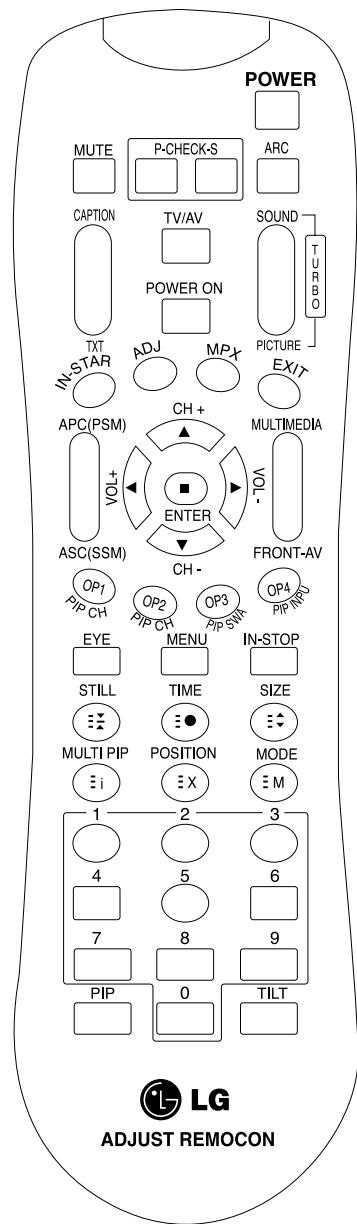
- Conduct Heat Run at the RF fog signals for more than 30 minutes.

2.2.1.2 Auto Gain/Offset adjustment

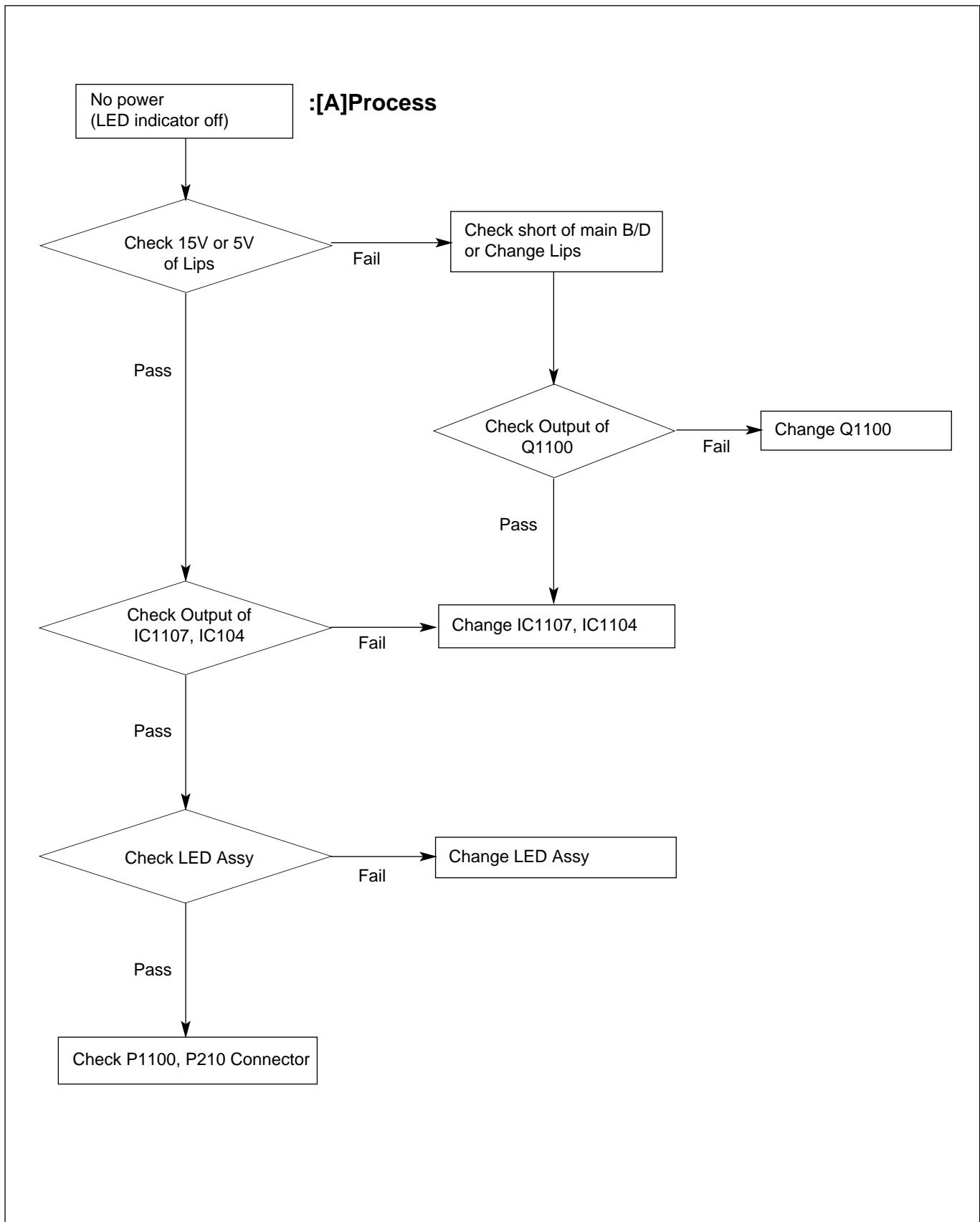
- Press IN-START Key to convert to the adjustment mode using the adjustment (SVC) remote controller, and press VOL+ Key at the Auto Gain menu.
- Once the adjustment is completed, press the Enter Key to save and finish the adjustment.

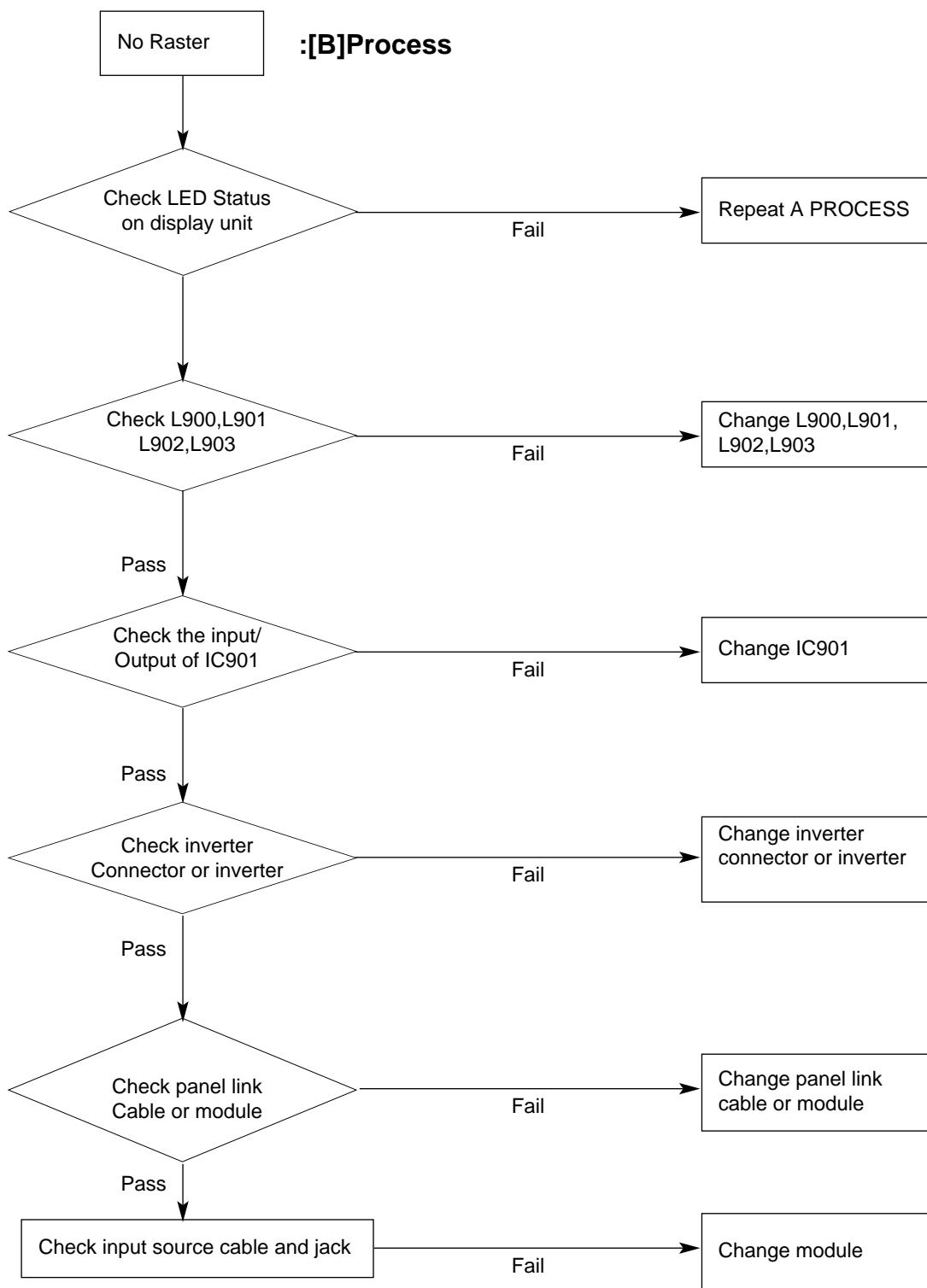
SVC REMOCON

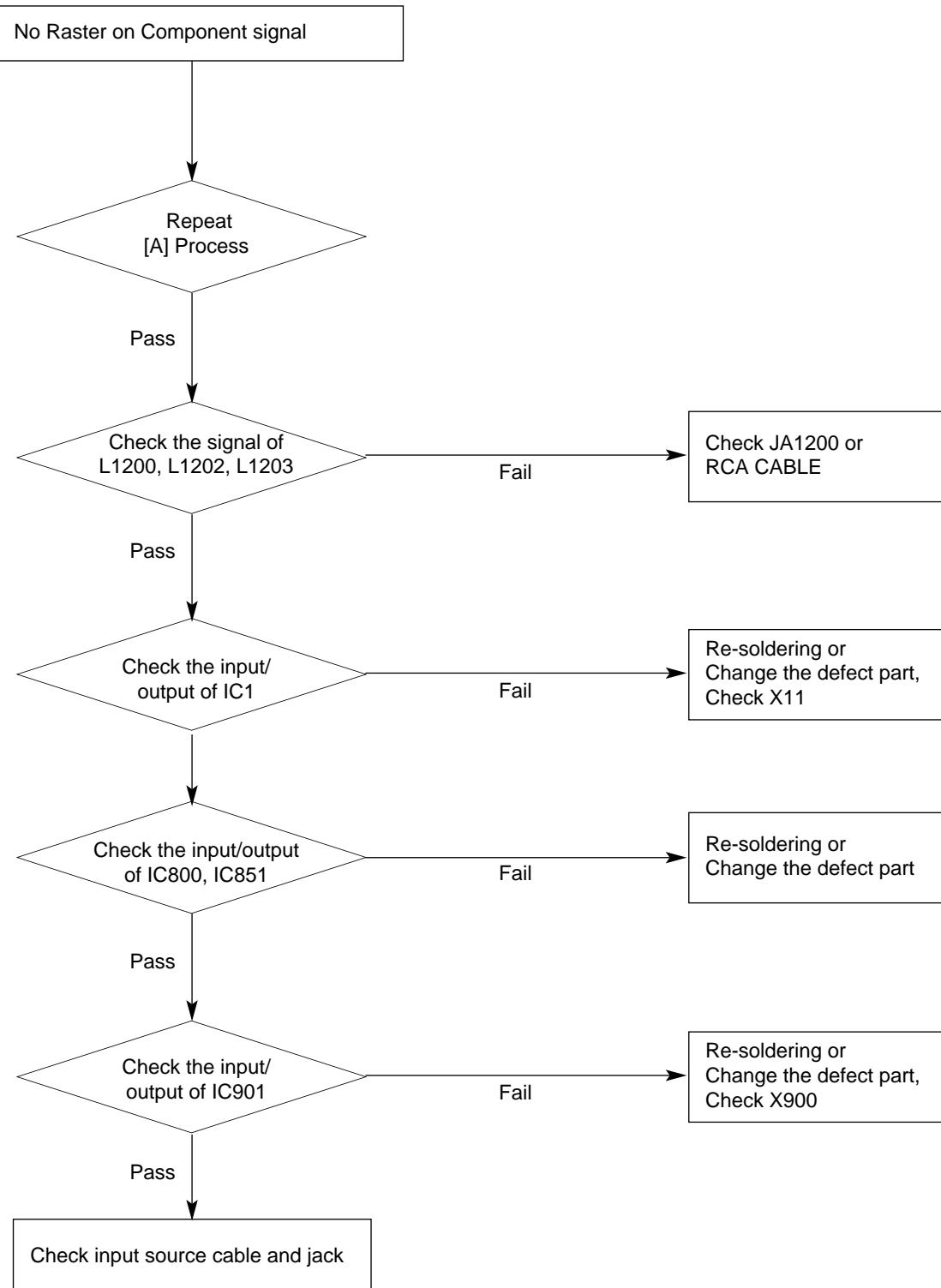
NO	KEY	FUNTION	REAMARK
1	POWER	To turn the TV on or off	
2	POWER ON	To turn the TV on automatically if the power is supplied to the TV. (Use the POWER key to deactivate): It should be deactivated when delivered.	
3	MUTE	To activate the mute function.	
4	P-CHECK	To check TV screen image easily.	Shortcut keys
5	S-CHECK	To check TV screen sound easily	Shortcut keys
6	ARC	To select size of the main screen (Normal, Spectacle, Wide or Zoom)	Shortcut keys
7	CAPTION	Switch to closed caption broadcasting	
8	TXT	To toggle on/off the teletext mode	
9	TV/AV	To select an external input for the TV screen	
10	TURBO SOUND	To start turbo sound	
11	TURBO PICTURE	To start turbo picture	
12	IN-START	To enter adjustment mode when manufacturing the TV sets.	Use the AV key to enter the screen W/B adjustment mode.
		To adjust the screen voltage (automatic): In-start → mute → Adjust → AV(Enter into W/B adjustment mode)	
		W/B adjustment (automatic): After adjusting the screen →W/B adjustment →Exit two times (Adjustment completed)	
		To enter into the adjustment mode. To adjust horizontal line and sub-brightness.	
13	ADJ	To select the multiple sound mode (Mono, Stereo or Foreign language)	
14	MPX	To release the adjustment mode	
15	EXIT	To easily adjust the screen according to surrounding brightness	
16	ASC(SSM)	To easily adjust sound according to the program type	
17	MULTIMIDIA	To check component input	Shortcut keys
18	FRONT-AV	To check the front AV	Shortcut keys
19	CH ±	To move channel up/down or to select a function displayed on the screen.	
20	VOL ±	To adjust the volume or accurately control a specific function.	
21	ENTER	To set a specific function or complete setting.	
22	PIP CH-(OP1)	To move the channel down in the PIP screen. To use as a red key in the teletext mode	
23	PIP CH+(OP2)	To move the channel in the PIP screen To use as a green key in the teletext mode	
24	PIP SWAP(OP3)	To switch between the main and sub screens To use as a yellow key in the teletext mode	
25	PIP INPUT(OP4)	To select the input status in the PIP screen To use as a blue key in the teletext mode	
26	EYE	To set a function that will automatically adjust screen status to match the surrounding brightness so natural color can be displayed.	
27	MENU	To select the functions such as video, voice, function or channel.	
28	IN-STOP	To set the delivery condition status after manufacturing the TV set.	
29	STILL	To halt the main screen in the normal mode, or the sub screen at the PIP screen. Used as a hold key in the teletext mode (Page updating is stopped.)	
30	TIME	Displays the teletext time in the normal mode Enables to select the sub code in the teletext mode	
31	SIZE	Used as the size key in the PIP screen in the normal mode Used as the size key in the teletext mode	
32	MULTI PIP	Used as the index key in the teletext mode (Top index will be displayed if it is the top text.)	
33	POSITION	To select the position of the PIP screen in the normal mode Used as the update key in the teletext mode (Text will be displayed if the current page is updated.)	
34	MODE	Used as Mode in the teletext mode	
35	PIP	To select the simultaneous screen	
36	TILT	To adjust screen tilt	Shortcut keys
37	0~9	To manually select the channel.	

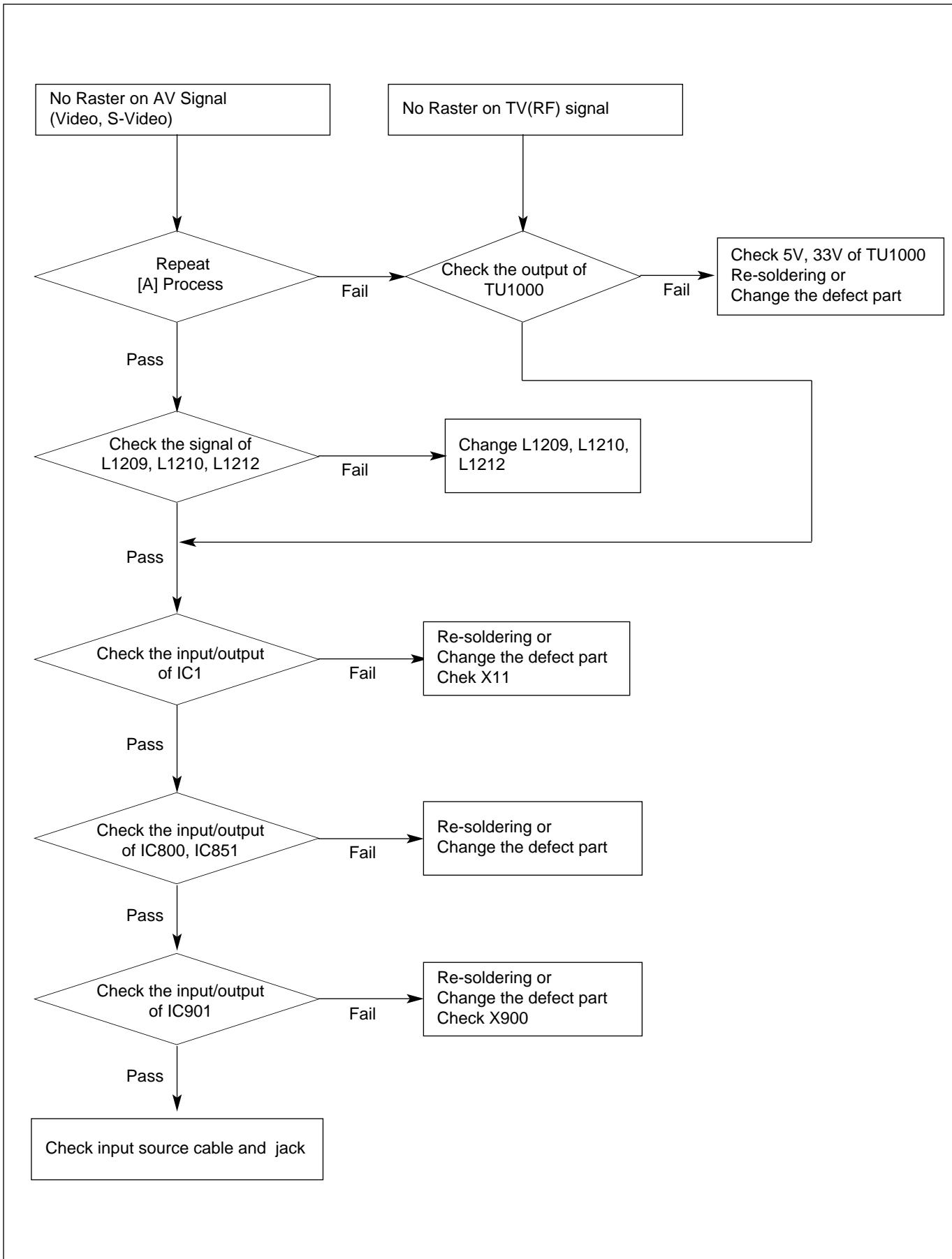


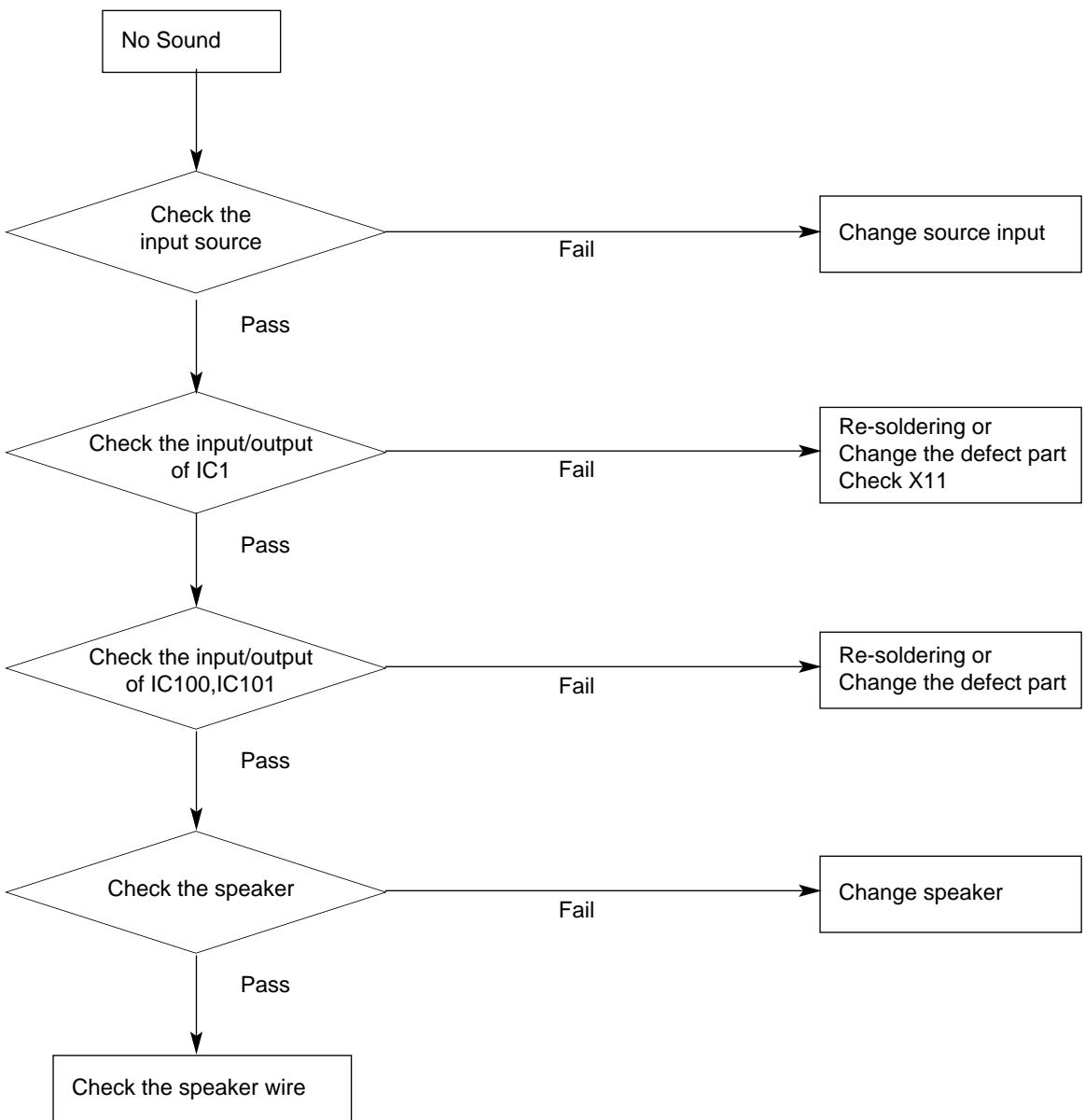
TROUBLESHOOTING



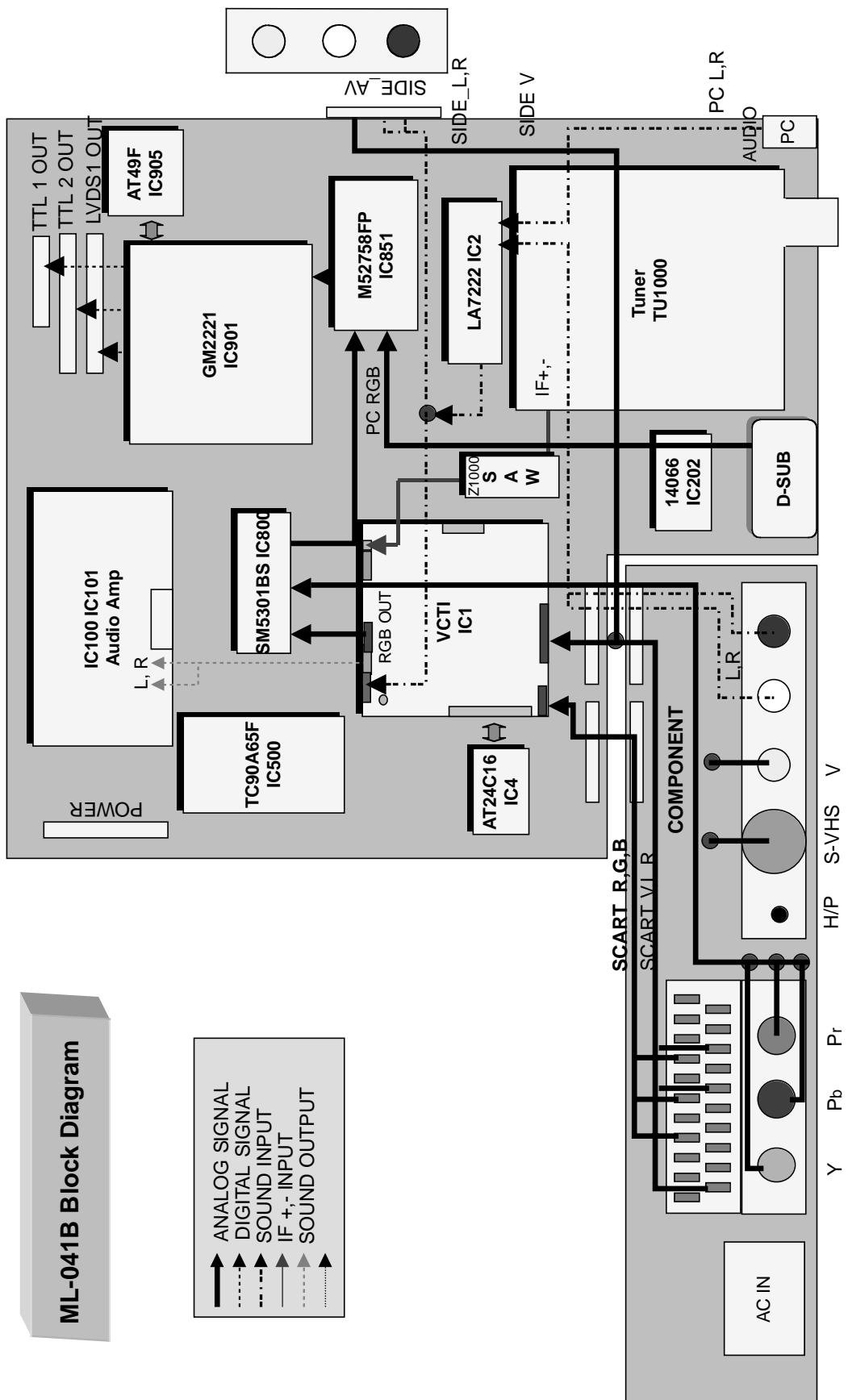








BLOCK DIAGRAM



BLOCK DIAGRAM DESCRIPTION

1. Video Controller Unit & Display Data Conversion Unit

The video controller unit receives the video signals inputted through the tuner, AV port (AV1, AV2, S-Video, component), and converts them into an analog RGB signal through the microcomputer (VCTI) combined with the video decoder that integrates various functions in one chip.

Either the analog RGB, component YPbPr or PC RGB signal is selected by the switching IC and inputted to a scaler (GM2221), which is sent to the LCD module after being modified to an LVDS signal through the integrated LVDS IC.

Or, it is sent to the LCD module as a TTL output.

VCTI is the main microprocessor that handles video signal processing and sound signal processing. It also manages the RF signals received from the tuner.

The scaler can control timing to fit into the LCD panel, and can also control the size and position of the input signal.

2. Power Supply Unit

The power supply unit provides 15V and 5V DC power to the mainboard.

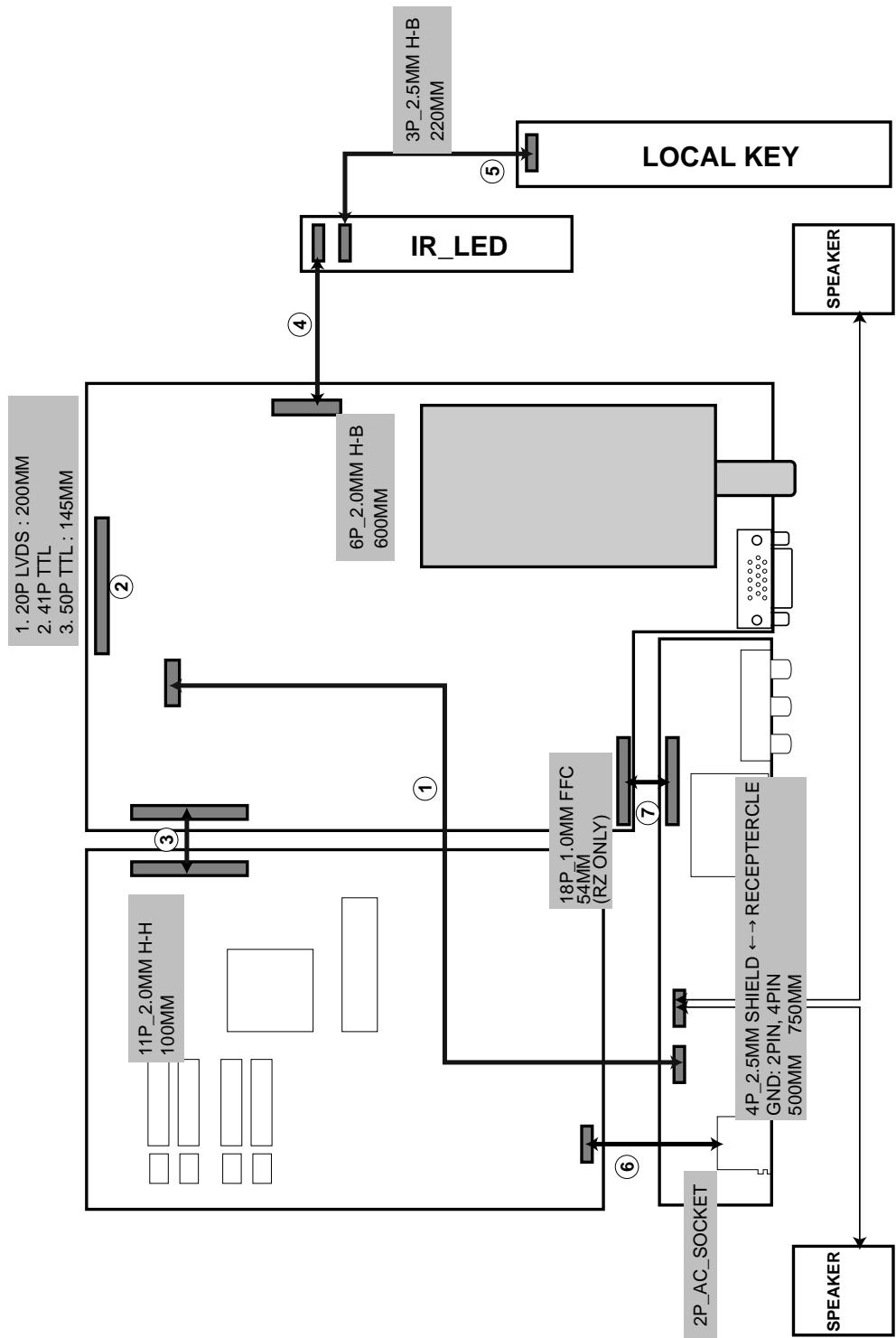
The PWM Step-Up DC/DC Converter circuit is used to generate the 33V used for the tuner.

15V power is directly used by the sound amplifier IC and is also used to generate 5V power through the regulator. 12V power is used for the LCD panel power, and 5V power is converted to 3.3V and 1.8V power through the regulator, which in turn supplies electrical power for ICs such as VCTI and scaler.

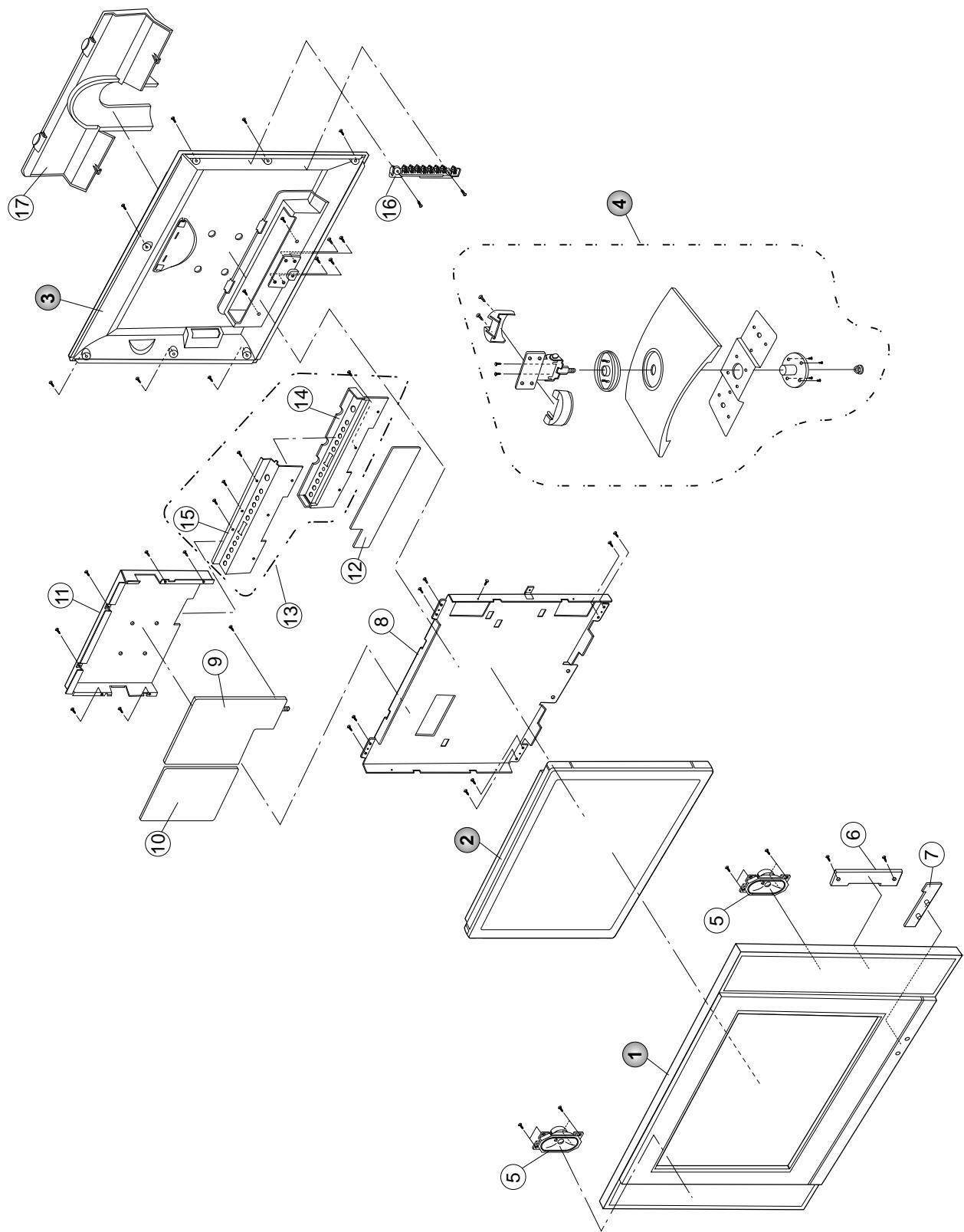
WIRING DIAGRAM

Wiring Part List

No.	Part No.
1	6631T25019Y
2	6631T11017P
3	6631T20028G
4	6631T20033G
5	6631T25021A
6	6620K00007C
7	6631T11017R



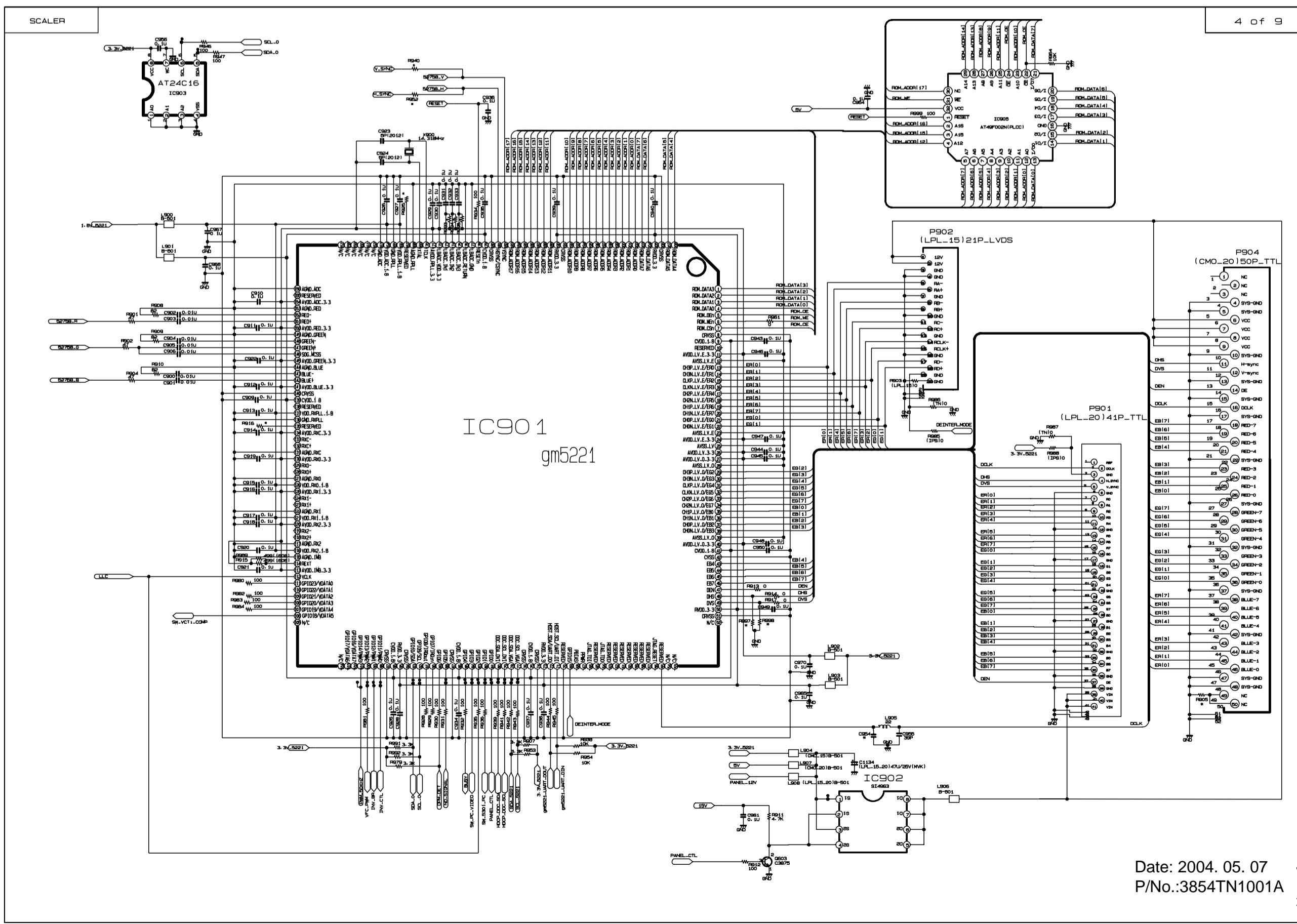
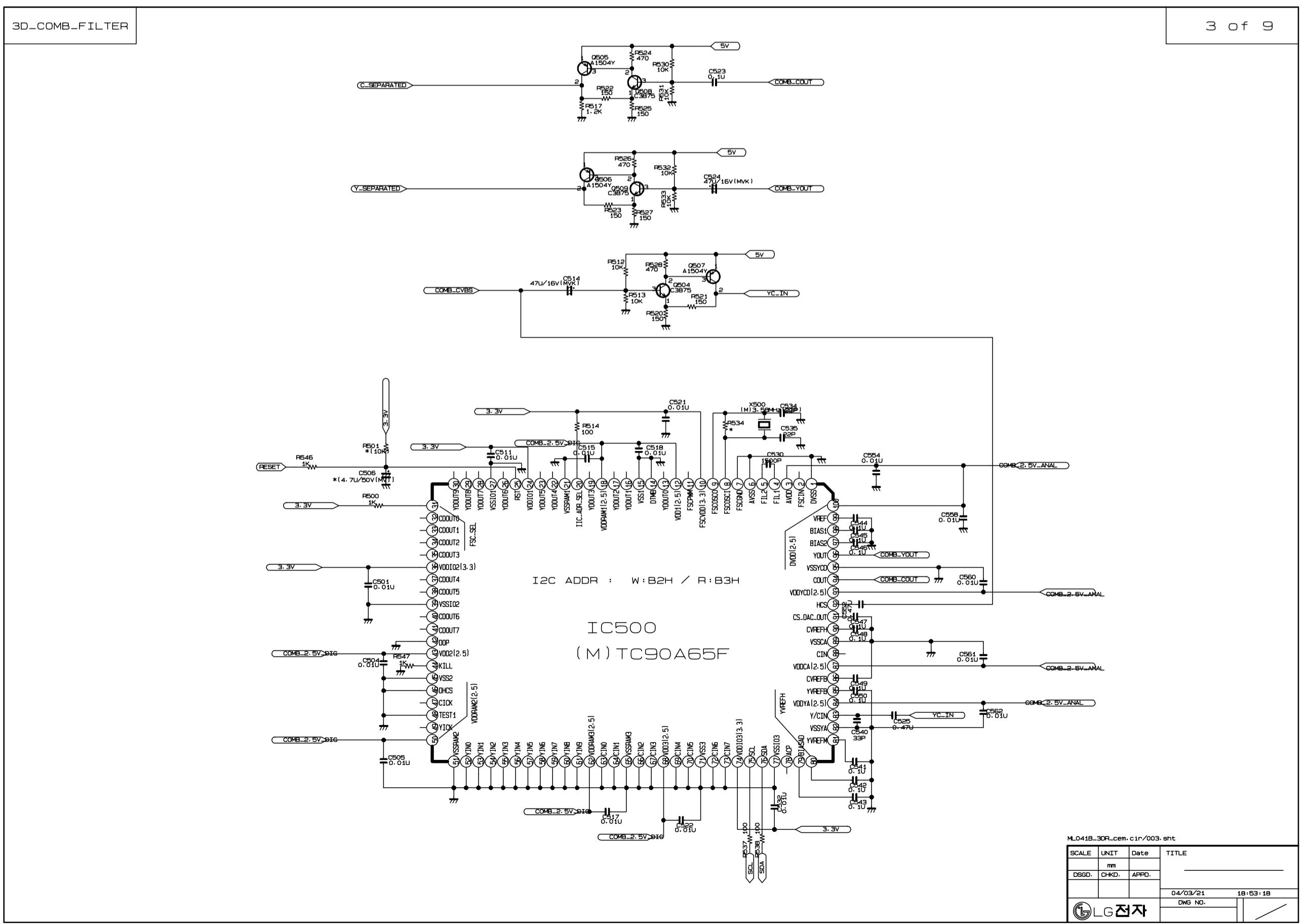
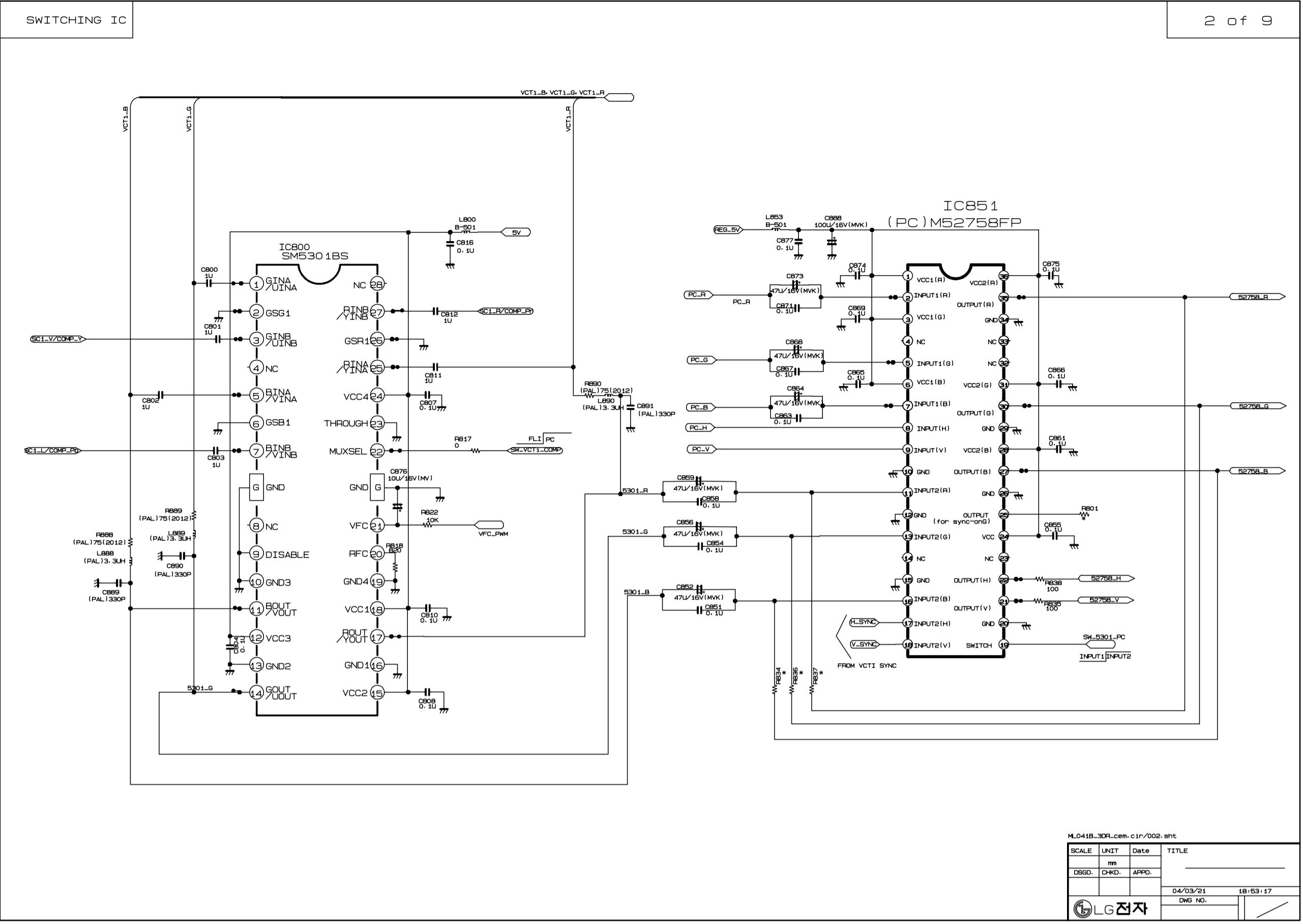
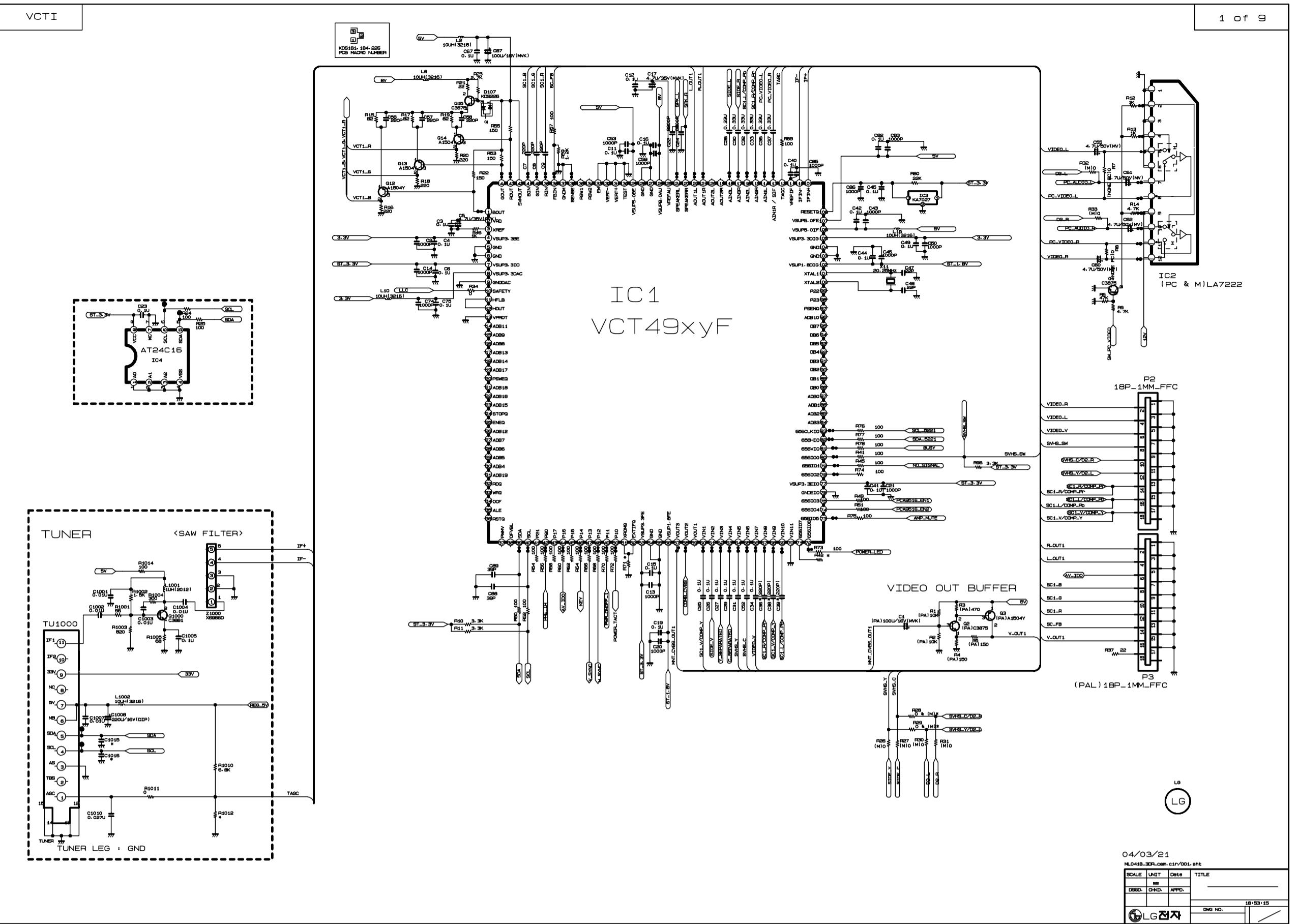
EXPLODED VIEW

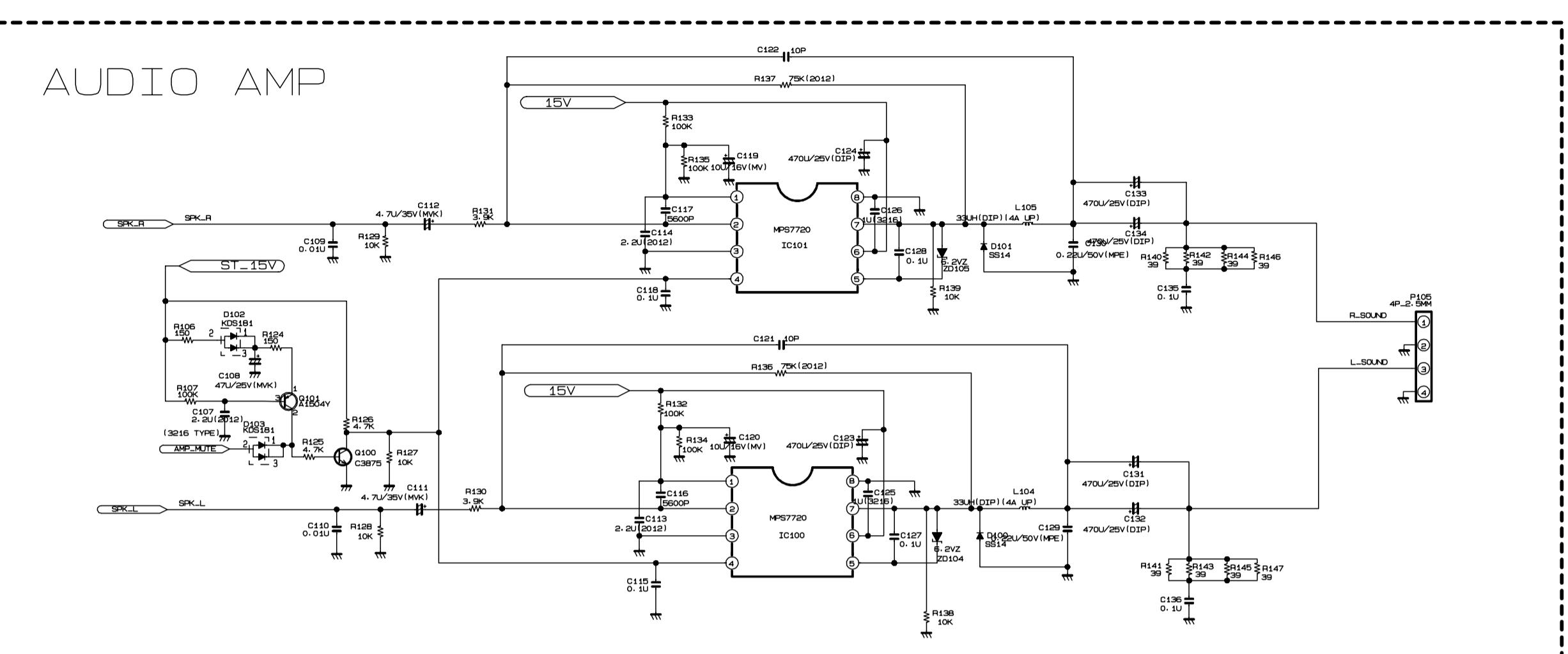


EXPLODED VIEW PARTS LIST

No.	PART NO.	DESCRIPTION
1	3091V00491N	CABINET ASSEMBLY, RZ-20LA62(SET) NON ML024G .
	3091TKD004B	CABINET ASSEMBLY, RZ-20LA66 BRAND 3090V00442 SKD .
2	6306V20002A	LCD(LIQUID CRYSTAL DISPLAY), V201V1-T02 VGA CHIMEI TFT COLOR NON
3	3809TKD003U	BACK COVER ASSEMBLY, RZ-20LA66 3808V00366 3508VC0002F
	3809TKD003N	BACK COVER ASSEMBLY, RT-20LA66 3808V00366 FOR THE CONTINET OF ASIA
	3809TKD003R	BACK COVER ASSEMBLY, RZ-20LA66 3808V00366 ML-041B C/SKD
	3809TKD003S	BACK COVER ASSEMBLY, RZ-20LA66 3808V00366 3850VC002G C/SKD
4	4811V00045D	BRACKET ASSEMBLY, STAND RZ-20LA60 ML012B .
	4811V00045G	BRACKET ASSEMBLY, STAND RZ-20LA60 ML012B C/SKD.
5	6400GKTX01C	SPEAKER,FULLRANGE, F1527C-6428-4 K-TONE FULL-RANGE(GENERAL) 4 OHM 7/12W 85DB OTHERS 40*70MM TRACK TYPE
6	6871TST633A	PWB(PCB) ASSEMBLY,SUB, RM-15LA66 SUB TOTAL BRAND CONTROL BOARD
7	6871TST679A	PWB(PCB) ASSEMBLY,SUB, RZ-20LA66_CMO SUB TOTAL BRAND IR B/D ML-041B
8	4950TKS279C	METAL, FRAME SBHG1-A(1.2T) FOR CMO_TN MODULE
	4950TKS279F	METAL, FRAME FOR CMO MODULE, CKD
9	3313TP2029A	MAIN TOTAL ASSEMBLY, RZ-20LA70(CMO) BRAND ML-041B
10	6871TPT280A	PWB(PCB) ASSEMBLY,POWER, RM-20LA77 POWER TOTAL LIEN CHANG LIPS FOR CMO/AUO
11	4951TKK186A	METAL ASSEMBLY, SHIELD REAR RM-20LA77
	4951TKK186B	METAL ASSEMBLY, SHIELD RM-20LA77 CKD
12	6871TST615A	PWB(PCB) ASSEMBLY, SUB, RZ-17LZ50 SUB TOTAL BRAND JACK(SCART) BOARD ASSY
13	3551TKK526J	COVER ASSEMBLY, RZ-20LA66 REAR A/V ML041B
	3551TKK526P	COVER ASSEMBLY, RZ-20LA66 REAR A/V LGENT, PHANTOM OF J
14	4810V00925G	BRACKET, REAR AV RZ-15LA66 ML024E HIPS 407AF 70B SPRAY
15	4950TKK916B	METAL, PLATE 15,20LA70 REAR A/V ""B"" TYPE"
16	5020V00776B	BUTTON, CONTROL RU-20LA60 ABS, HF-380 8KEY ."
17	3550V00297B	COVER, REAR AV RU-20LA60 ABS, HF-380 ."

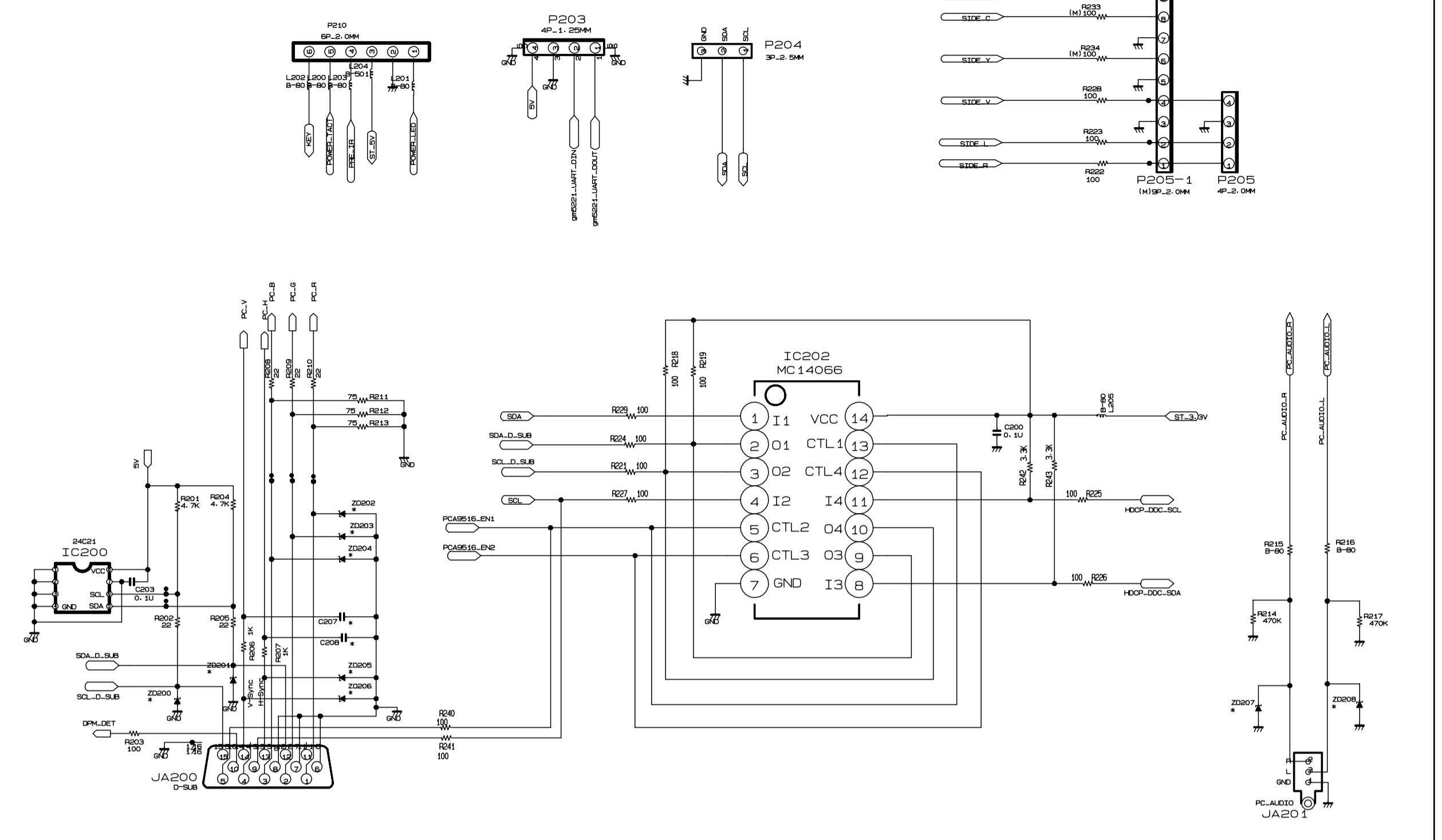
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*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
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		R10	0RJ3301D677	3.3K OHM 1/10 W 5% 1608 R/TP
		R1001	0RJ0562D677	56 OHM 1/10 W 5% 1608 R/TP
		R1003	0RJ8200D677	820 OHM 1/10 W 5% 1608 R/TP
		R1005	0RJ0682D677	68 OHM 1/10 W 5% 1608 R/TP
		R1014	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R11	0RJ3301D677	3.3K OHM 1/10 W 5% 1608 R/TP
		R1105	0RJ1001D677	1K OHM 1/10 W 5% 1608 R/TP
		R1107	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R1149	0RH1002D622	10K OHM 1 / 10 W 2012 5.00%
		R1150	0RJ0102D677	10 OHM 1/10 W 5% 1608 R/TP
		R124	0RJ1500D677	150 OHM 1/10 W 5% 1608 R/TP
		R125	0RJ4701D677	4.7K OHM 1/10 W 5% 1608 R/TP
		R127	0RJ2701D677	2.7K OHM 1/10 W 5% 1608 R/TP
		R130	0RJ1202D677	12K OHM 1/10 W 5% 1608 R/TP
		R131	0RJ1202D677	12K OHM 1/10 W 5% 1608 R/TP
		R138	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP
		R139	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP
		R15	0RJ0822D677	82 OHM 1/10 W 5% 1608 R/TP
		R16	0RJJ2200D677	220 OHM 1/10 W 5% 1608 R/TP
		R17	0RJ0822D677	82 OHM 1/10 W 5% 1608 R/TP
		R18	0RJJ2200D677	220 OHM 1/10 W 5% 1608 R/TP
		R19	0RJ0822D677	82 OHM 1/10 W 5% 1608 R/TP
		R2	0RJ1002D677	10K OHM 1/10 W 5% 1608 R/TP
		R20	0RJJ2200D677	220 OHM 1/10 W 5% 1608 R/TP
		R203	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R21	0RJ0222D677	22 OHM 1/10 W 5% 1608 R/TP
		R22	0RJ1500D677	150 OHM 1/10 W 5% 1608 R/TP
		R221	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R224	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R225	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R226	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R227	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R229	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R23	0RJ2701D677	2.7K OHM 1/10 W 5% 1608 R/TP
		R24	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
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		R29	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R3	0RJ4700D677	470 OHM 1/10 W 5% 1608 R/TP
		R34	0RJ0000D677	0 OHM 1/10 W 5% 1608 R/TP
		R4	0RJ1500D677	150 OHM 1/10 W 5% 1608 R/TP
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		R60	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R62	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
		R64	0RJ1000D677	100 OHM 1/10 W 5% 1608 R/TP
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		X11	6202VDT002E	SX-1SMD SUNNY RADIAL 2025000
		X900	6202VDT002B	SX-1 SUNNY SC14.3MHZ +/- 30
		IC905	6620F00017A	CCSD-32T-SM WOYOYOUNG 32P PLC
		TU1000	6700VS0003A	TAEW-G051D LG INOTEK MULTI V
CONTROL BOARD				
		R2200	ORN1101F409	1.10K 1/6W 1% TA52
		R2201	ORN8200F409	820 1/6W 1% TA52



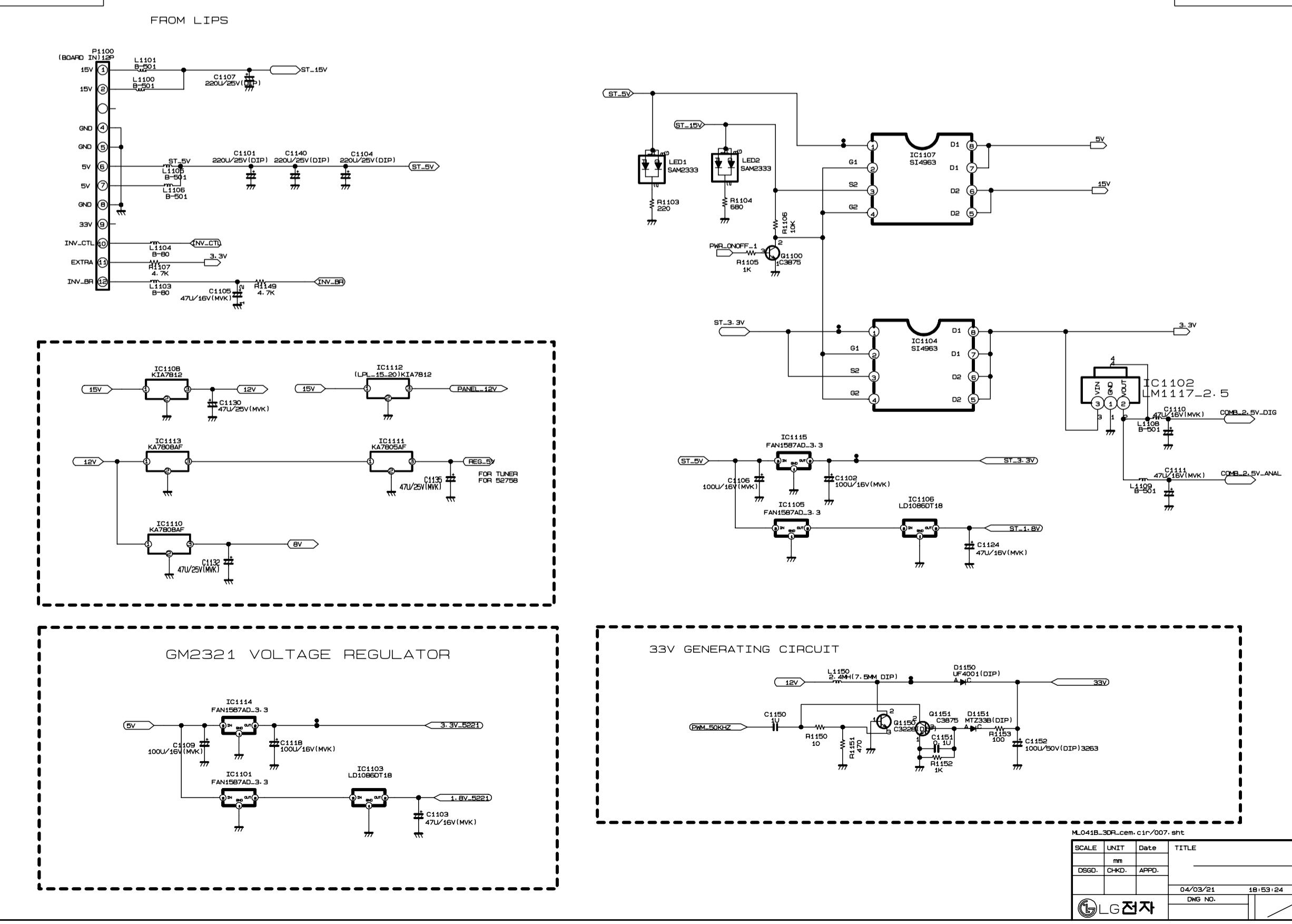


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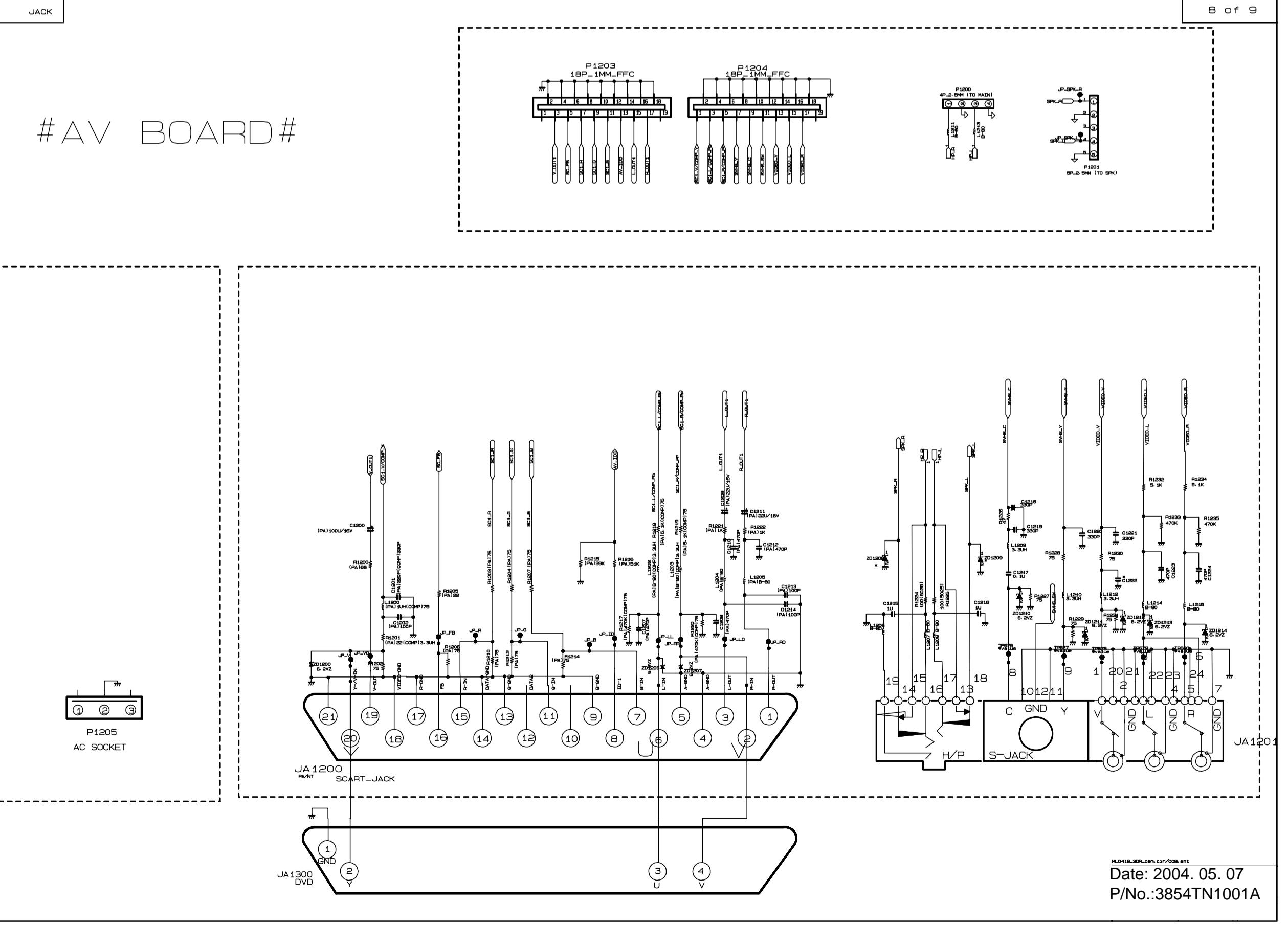
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